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(12) **United States Design Patent**  
**Shain**

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(54) **SENSOR MODULE**

(71) Applicant: **FLIR Systems, Inc.**, Wilsonville, OR (US)

(72) Inventor: **Chaim Shain**, Parkland, FL (US)

(73) Assignee: **FLIR Systems, Inc.**, Wilsonville, OR (US)

(\*\*) Term: **15 Years**

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(51) **LOC (13) Cl.** ..... **16-05**

(52) **U.S. Cl.**  
USPC ..... **D16/219**

(58) **Field of Classification Search**  
USPC ..... D10/52, 60; D16/136, 200, 219; D14/217  
CPC ..... H01R 13/6275; H01R 43/26; H01R 13/5219; G01J 5/0806; G01J 5/10; G01J 1/0233; G01J 5/0809; H04N 5/23203; H04N 5/33; H04N 5/332; H04N 5/335; H04N 5/2252; H04N 7/183; G08B 13/19632; G08B 13/19619

See application file for complete search history.

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*Primary Examiner* — Holly E Thurman

*Assistant Examiner* — Ieisha N Price

(74) *Attorney, Agent, or Firm* — Haynes and Boone, LLP

(57) **CLAIM**

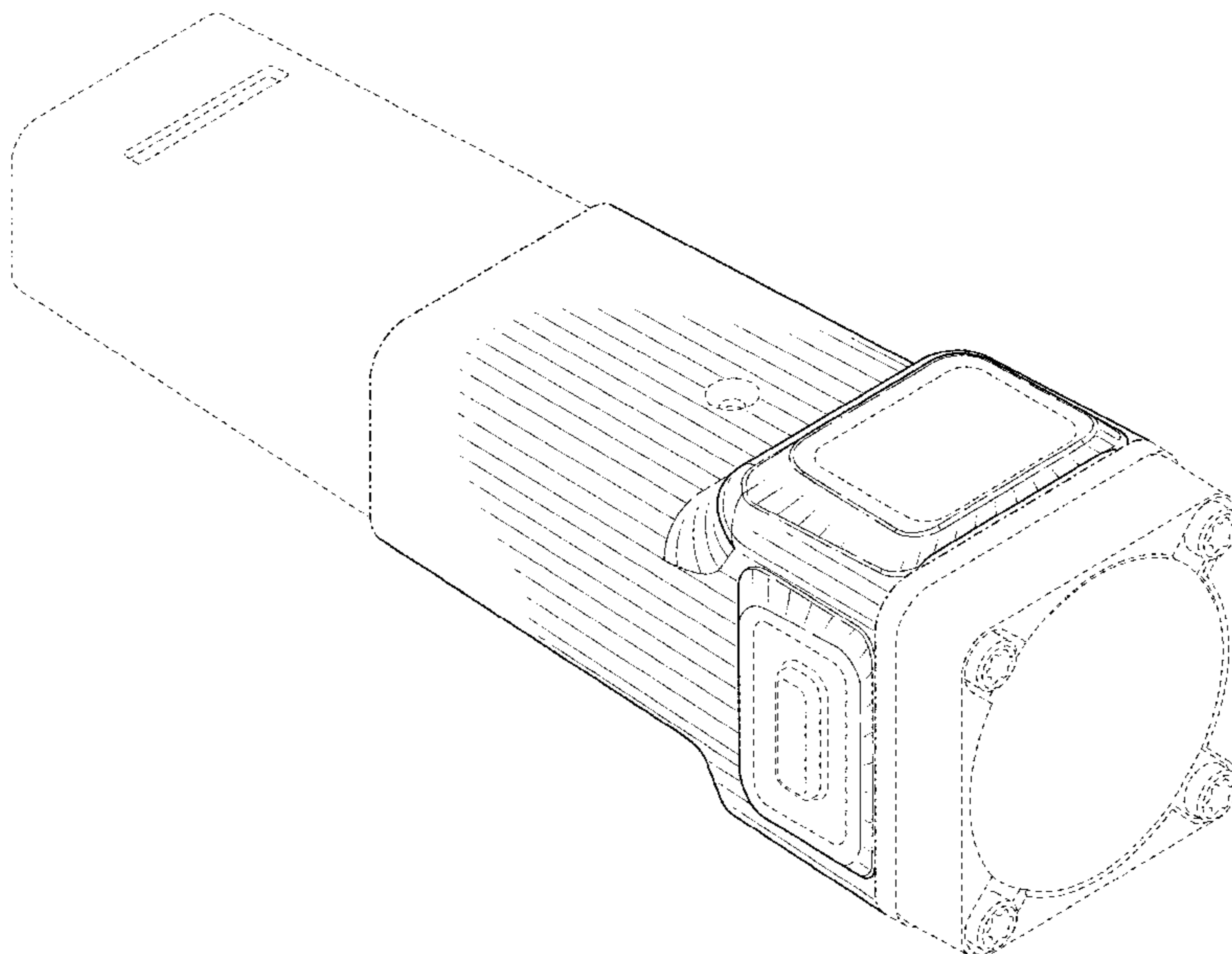
The ornamental design for a sensor module, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top, and right perspective view of a sensor module embodying the new design; FIG. 2 is a rear, bottom, and left perspective view thereof; FIG. 3 is a front elevational view thereof; FIG. 4 is a rear elevational view thereof; FIG. 5 is a right side view thereof; FIG. 6 is a left side view thereof; FIG. 7 is a top plan view thereof; and, FIG. 8 is a bottom plan view thereof.

The broken lines in the drawings illustrate portions of the sensor module and form no part of the claimed design. The dot-dash-dot broken lines in the drawings define the bounds of the claim and form no part thereof.

**1 Claim, 5 Drawing Sheets**



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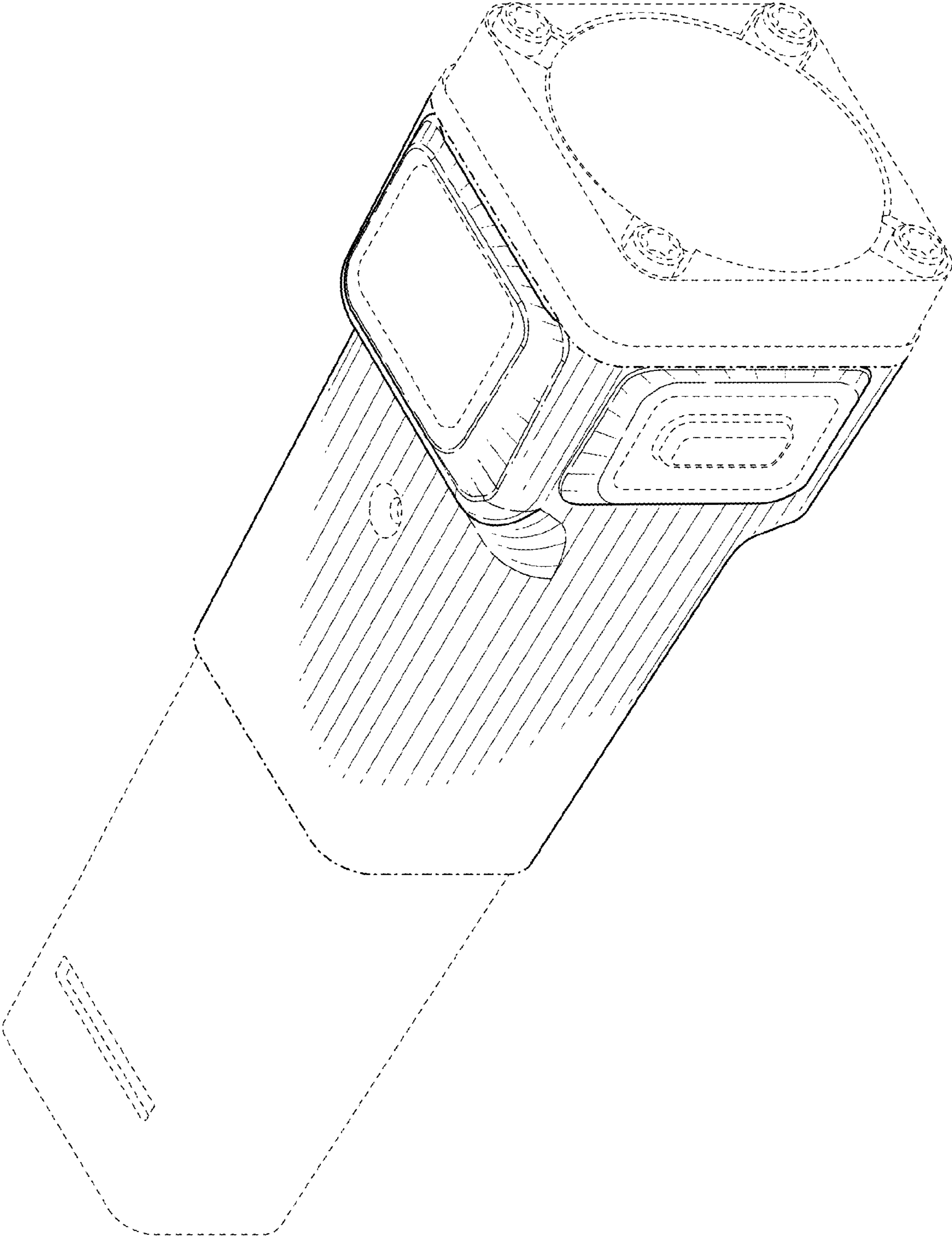


FIG. 1

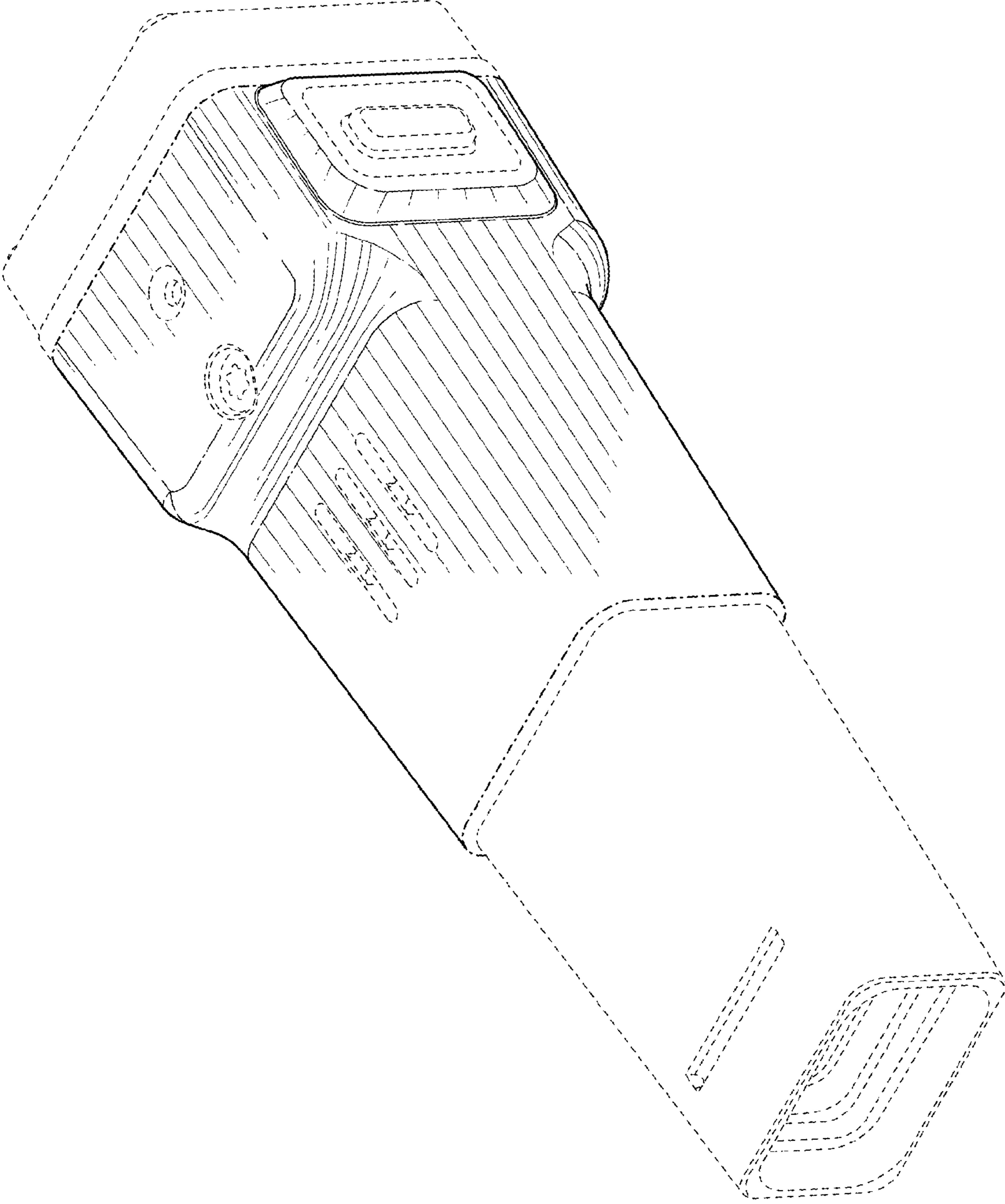


FIG. 2

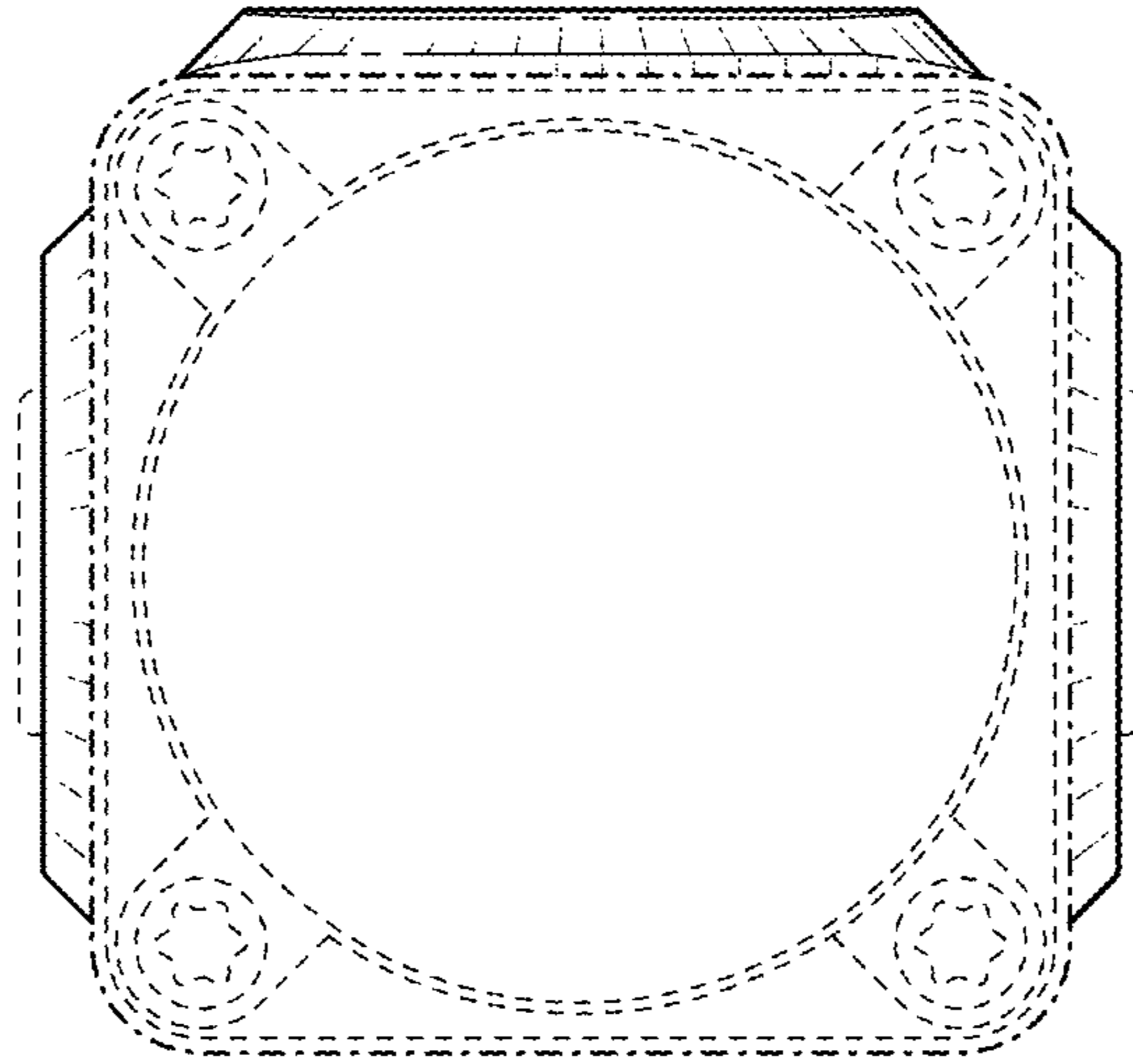


FIG. 3

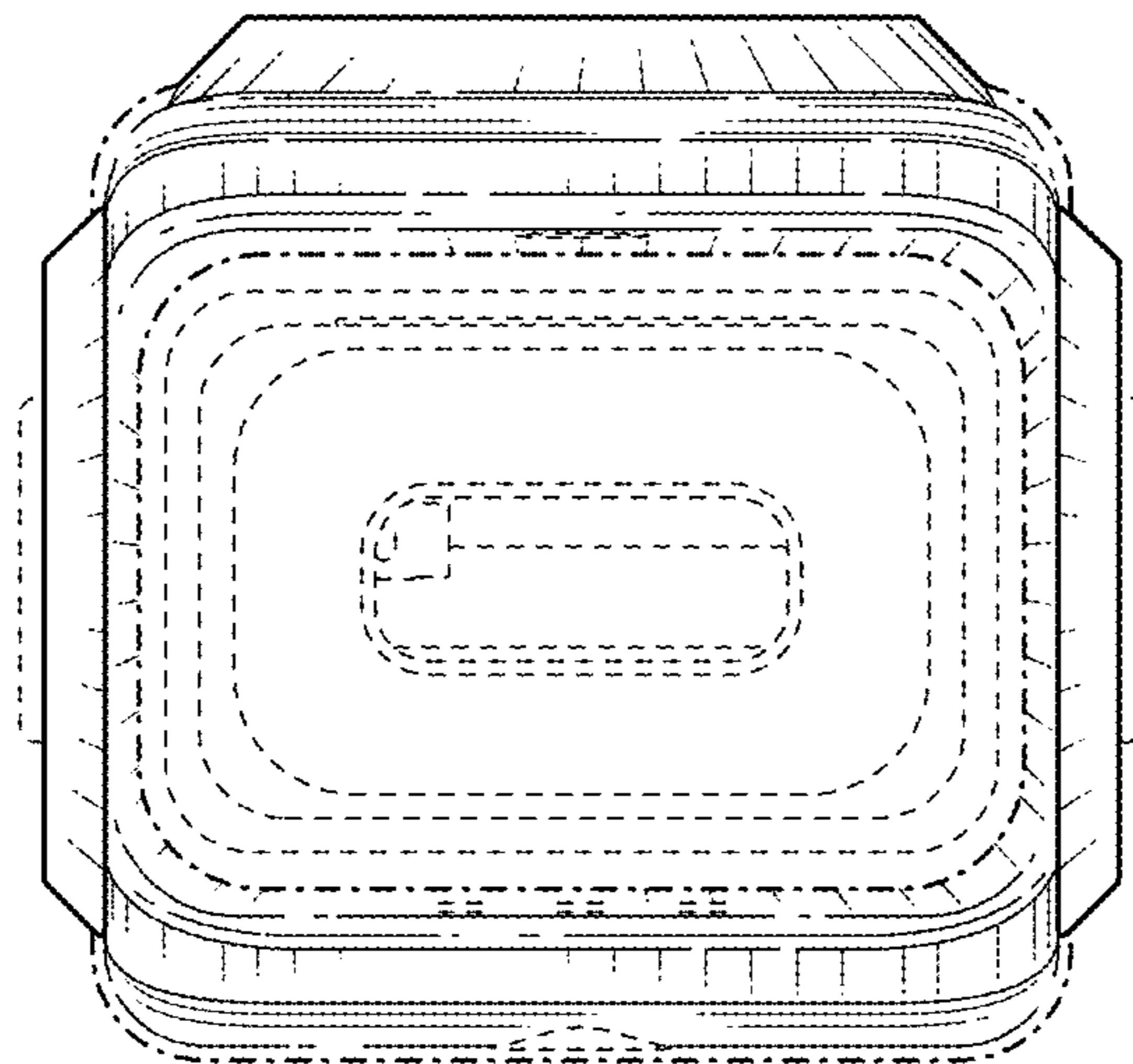


FIG. 4

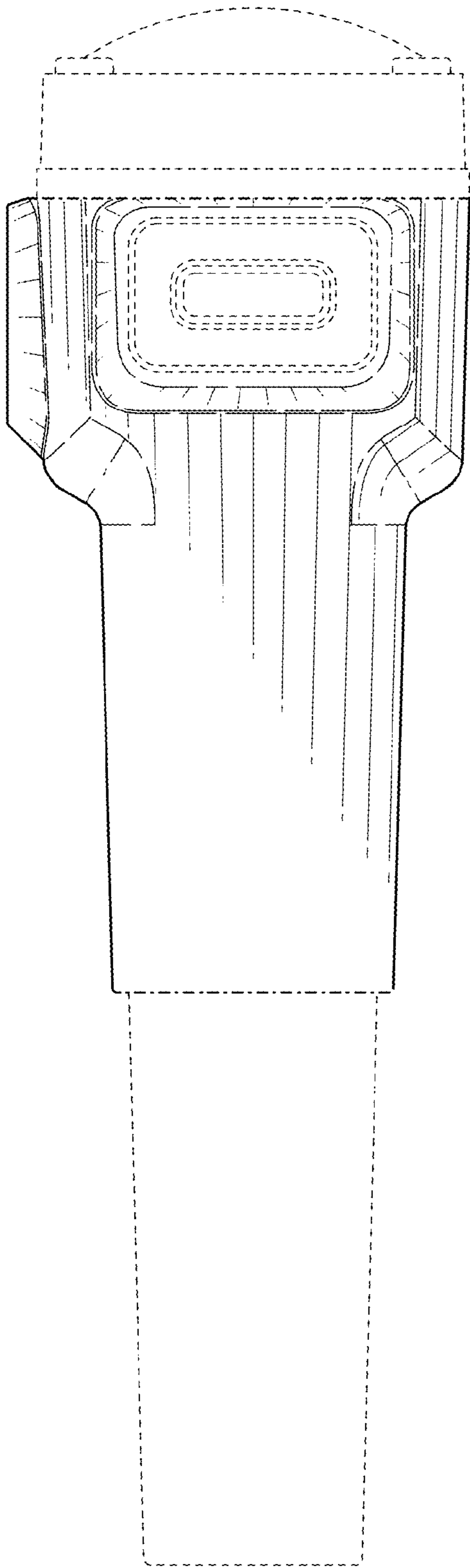


FIG. 5

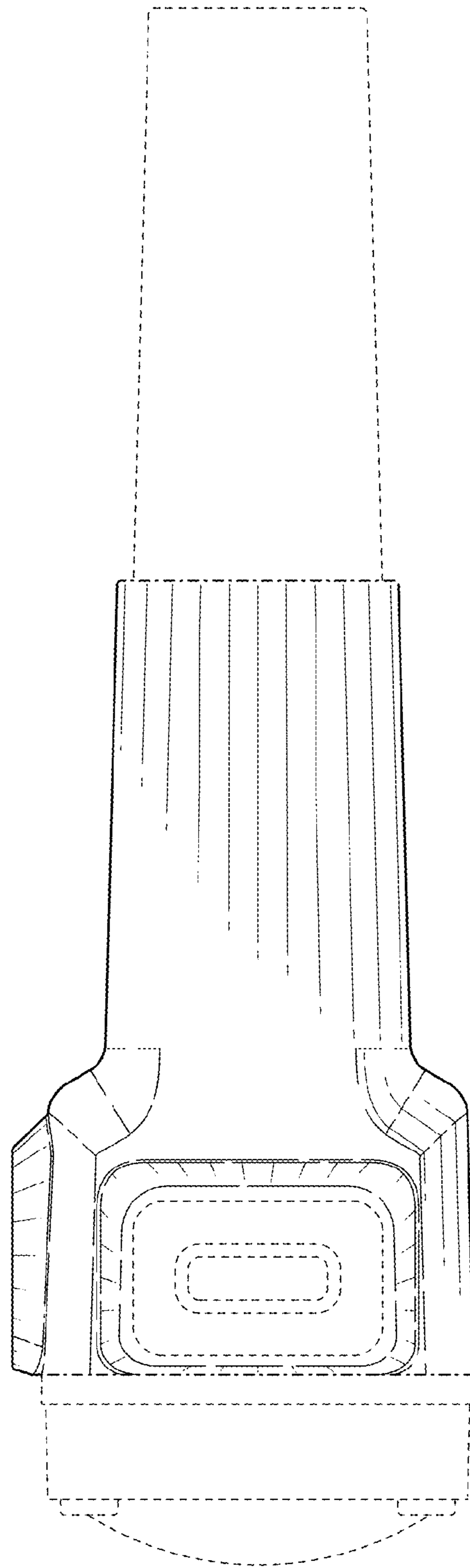


FIG. 6

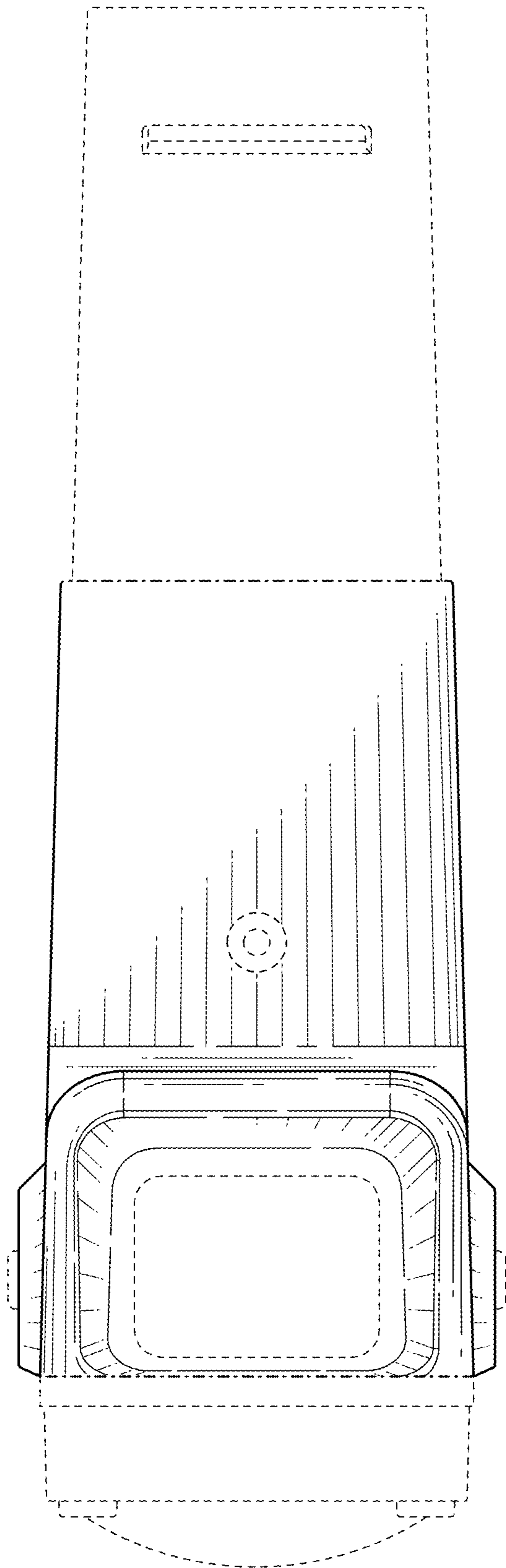


FIG. 7

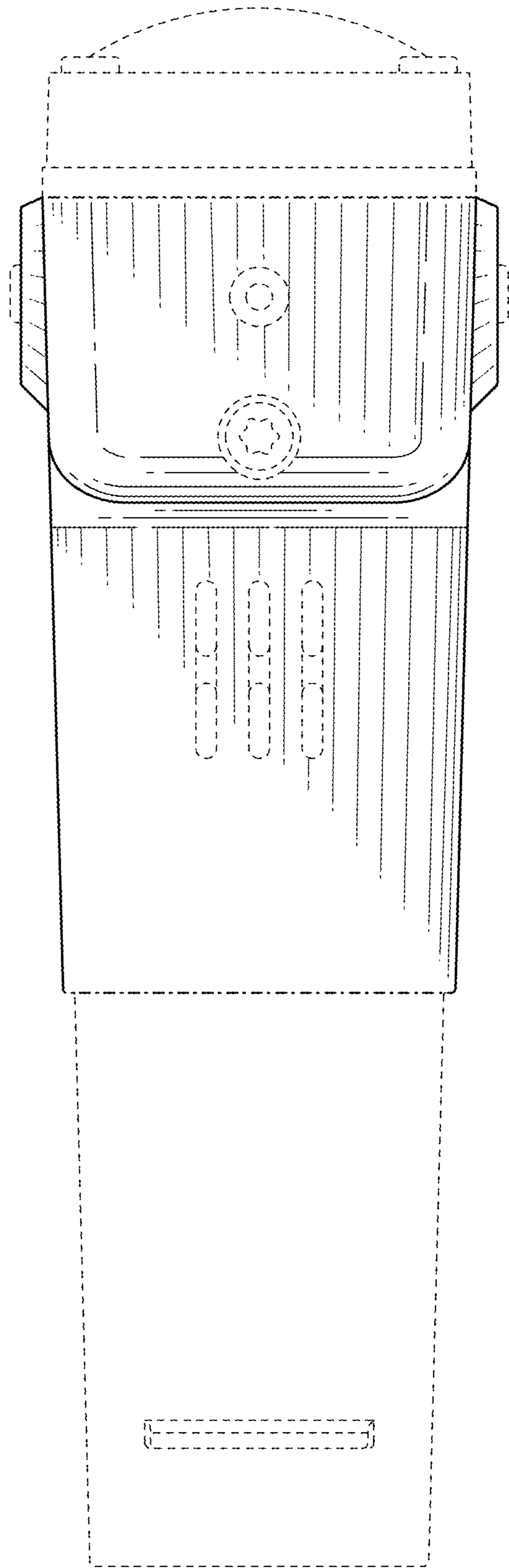


FIG. 8